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| (21) International Application Number: PCT/US95/15939<br>(22) International Filing Date: 7 December 1995 (07.12.95)<br>(30) Priority Data:<br>08/363,117 23 December 1994 (23.12.94) US<br>(71) Applicant: AMOCO CORPORATION [US/US]; Law Dept.,<br>Mail Code 1907A, 200 East Randolph Drive, P.O. Box<br>87703, Chicago, IL 60680 (US).<br>(72) Inventors: KARUNARATNE, Palitha, Mahendra, S.; Sunset<br>Lodge, 19 Sunset Close, Singapore 2159 (SG). SRINI-<br>VASAN, Visveswaran; Blk 468, Jurong West Street 41 #02-<br>461, Singapore 2264 (SG). CHUA, Manuel, Alameda, Jr.;<br>Blk 839, Jurong West Street 81 #10-97, Singapore 2264<br>(SG). CHIN, Neep, Hing; Blk 2, Lakepoint Drive #02-<br>17, Singapore 2264 (SG). ROUNDS, Nicholas, Andrew; 5<br>Meeting Street, Roswell, GA 30075 (US).<br>(74) Agent: KANADY, Mary, Jo; Amoco Corporation, Law Dept.,<br>Mail Code 1907A, 200 East Randolph Drive, P.O. Box<br>87703, Chicago, IL 60680 (US). |  |    | (81) Designated States: AM, AT, AU, BB, BG, BR, BY, CA, CH,<br>CN, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IS, JP, KE,<br>KG, KP, KR, KZ, LK, LR, LT, LU, LV, MD, MG, MN,<br>MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK,<br>TJ, TM, TT, UA, UG, UZ, VN, European patent (AT, BE,<br>CH, DE, DK, ES, FR, GB, GR, IE, IT, LU, MC, NL, PT,<br>SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML,<br>MR, NE, SN, TD, TG), ARIPO patent (KE, LS, MW, SD,<br>SZ, UG).<br><br>Published<br>With international search report. |

(54) Title: IMPROVED PROCESS FOR MAKING PREFORMS USEFUL FOR ENCAPSULATING SEMICONDUCTORS

(57) Abstract

Preform useful for encapsulating semiconductors and other electric or electronic devices are prepared by a process which comprises warming thermoset resin to form a melt, injecting it into a mold, and cooling to form a solidified molding, all without substantially curing the thermoset resin.

